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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	196
Number of Logic Elements/Cells	466
Total RAM Bits	6272
Number of I/O	112
Number of Gates	5000
Voltage - Supply	4.75V ~ 5.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc4005-5pq208c

Architectural Overview

The XC4000 families achieve high speed through advanced semiconductor technology and through improved architecture, and supports system clock rates of up to 50 MHz. Compared to older Xilinx FPGA families, the XC4000 families are more powerful, offering on-chip RAM and wide-input decoders. They are more versatile in their applications, and design cycles are faster due to a combination of increased routing resources and more sophisticated software. And last, but not least, they more than double the available complexity, up to the 20,000-gate level.

The XC4000 families have 16 members, ranging in complexity from 2,000 to 25,000 gates.

Logic Cell Array Families

Xilinx high-density user-programmable gate arrays include three major configurable elements: configurable logic blocks (CLBs), input/output blocks (IOBs), and interconnections. The CLBs provide the functional elements for constructing the user's logic. The IOBs provide the interface between the package pins and internal signal lines. The programmable interconnect resources provide routing paths to connect the inputs and outputs of the CLBs and IOBs onto the appropriate networks. Customized configuration is established by programming internal static memory cells that determine the logic functions and interconnections implemented in the LCA device.

The first generation of LCA devices, the XC2000 family, was introduced in 1985. It featured logic blocks consisting of a combinatorial function generator capable of implementing 4-input Boolean functions and a single storage element. The XC2000 family has two members ranging in complexity from 800 to 1500 gates.

In the second-generation XC3000A LCA devices, introduced in 1987, the logic block was expanded to implement wider Boolean functions and to incorporate a second flip-flop in each logic block. Today, the XC3000 devices range in complexity from 1,300 to 10,000 usable gates. They have a maximum guaranteed toggle frequency ranging from 70 to 270 MHz, equivalent to maximum system clock frequencies of up to 80 MHz.

The third generation of LCA devices further extends this architecture with a yet more powerful and flexible logic block. I/O block functions and interconnection options have also been enhanced with each successive generation, further extending the range of applications that can be implemented with an LCA device.

This third-generation architecture forms the basis of the XC4000 families of devices that feature logic densities up to 25,000 usable gates and support system clock rates of up to 50 MHz. The use of an advanced, sub-micron CMOS process technology as well as architectural improvements contribute to this increase in FPGA capabilities. However, achieving these high logic-density and performance levels also requires new and more powerful automated design tools. IC and software engineers collaborated during the definition of the third-generation LCA architecture to meet an important performance goal — an FPGA architecture and companion design tools for completely automatic placement and routing of 95% of all designs, plus a convenient way to complete the remaining few designs.

Configurable Logic Blocks

A number of architectural improvements contribute to the increased logic density and performance levels of the XC4000 families. The most important one is a more powerful and flexible CLB surrounded by a versatile set of routing resources, resulting in more "effective gates per CLB." The principal CLB elements are shown in Figure 1. Each new CLB also packs a pair of flip-flops and two independent 4-input function generators. The two function generators offer designers plenty of flexibility because most combinatorial logic functions need less than four inputs. Consequently, the design-software tools can deal with each function generator independently, thus improving cell usage.

Thirteen CLB inputs and four CLB outputs provide access to the function generators and flip-flops. More than double the number available in the XC3000 families, these inputs and outputs connect to the programmable interconnect resources outside the block. Four independent inputs are provided to each of two function generators (F1 – F4 and G1 – G4). These function generators, whose outputs are labeled F' and G', are each capable of implementing any arbitrarily defined Boolean function of their four inputs. The function generators are implemented as memory look-up tables; therefore, the propagation delay is independent of the function being implemented. A third function generator, labeled H', can implement any Boolean function of its three inputs: F' and G' and a third input from outside the block (H1). Signals from the function generators can exit the CLB on two outputs; F' or H' can be connected to the X output, and G' or H' can be connected to the Y output. Thus, a CLB can be used to implement any two independent functions of up-to-four variables, or any single function of five variables, or any function of four variables together with some functions of five variables , or it can implement even some functions of up to nine variables. Implementing wide functions in a single block reduces both the number of blocks required and the delay in the signal path, achieving both increased density and speed.

The two storage elements in the CLB are edge-triggered D-type flip-flops with common clock (K) and clock enable (EC) inputs. A third common input (S/R) can be programmed as either an asynchronous set or reset signal

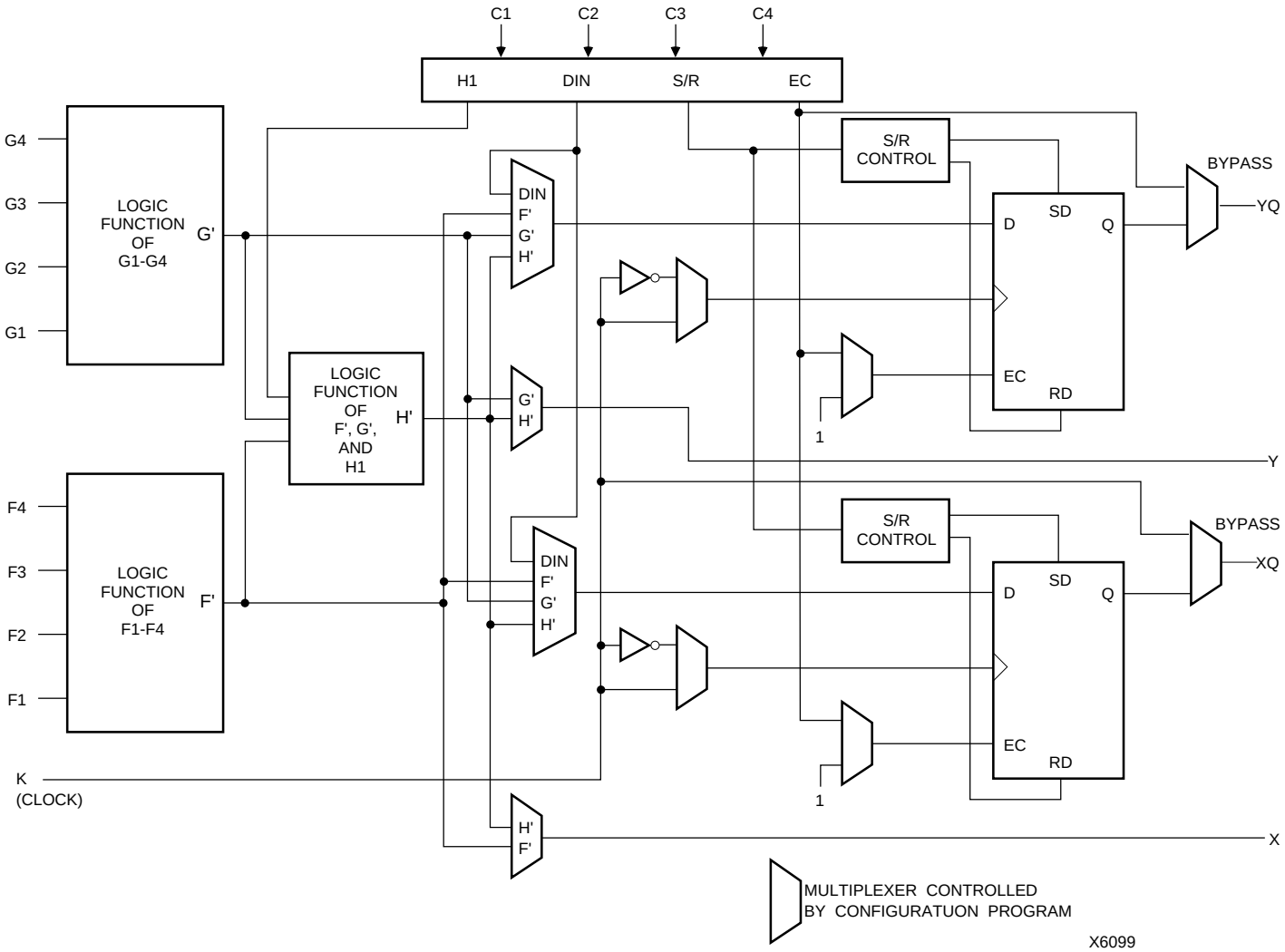


Figure 1. Simplified Block Diagram of XC4000-Families Configurable Logic Block

independently for each of the two registers; this input also can be disabled for either flip-flop. A separate global Set/Reset line (not shown in Figure 1) sets or clears each register during power-up, reconfiguration, or when a dedicated Reset net is driven active. This Reset net does not compete with other routing resources; it can be connected to any package pin as a global reset input.

Each flip-flop can be triggered on either the rising or falling clock edge. The source of a flip-flop data input is programmable: it is driven either by the functions F', G', and H', or the Direct In (DIN) block input . The flip-flops drive the XQ and YQ CLB outputs.

In addition, each CLB F' and G' function generator contains dedicated arithmetic logic for the fast generation of carry and borrow signals, greatly increasing the efficiency and performance of adders, subtracters, accumulators, comparators and even counters.

Multiplexers in the CLB map the four control inputs, labeled C1 through C4 in Figure 1, into the four internal control signals (H1, DIN, S/R, and EC) in any arbitrary manner.

The flexibility and symmetry of the CLB architecture facilitates the placement and routing of a given application. Since the function generators and flip-flops have independent inputs and outputs, each can be treated as a separate entity during placement to achieve high packing density. Inputs, outputs, and the functions themselves can freely swap positions within a CLB to avoid routing congestion during the placement and routing operation.

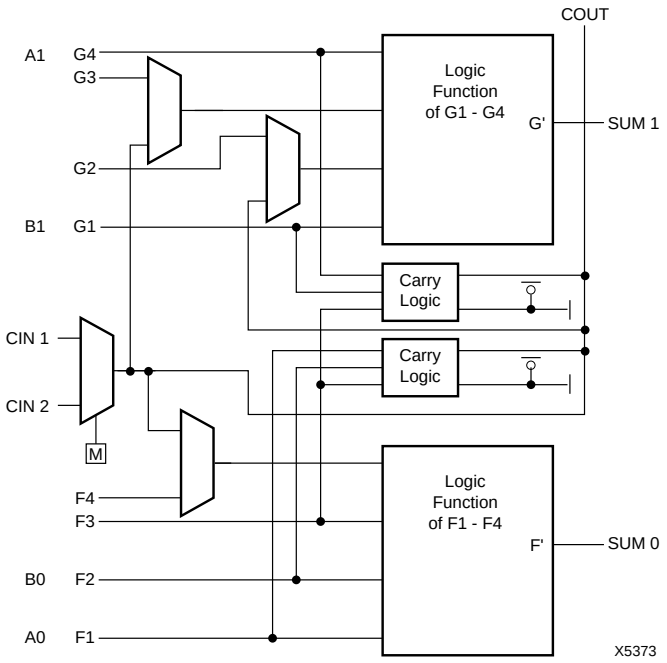


Figure 2. Fast Carry Logic in Each CLB

up/down counter, this means twice the speed in half the number of CLBs, compared with the XC3000 families.

Pipelining Speeds Up The System: The abundance of flip-flops in the CLBs invites pipelined designs. This is a powerful way of increasing performance by breaking the function into smaller subfunctions and executing them in parallel, passing on the results through pipeline flip-flops. This method should be seriously considered wherever total performance is more important than simple through-delay.

Wide Edge Decoding: For years, FPGAs have suffered from the lack of wide decoding circuitry. When the address or data field is wider than the function generator inputs (five bits in the XC3000 families), FPGAs need multi-level decoding and are thus slower than PALs. The XC4000-family CLBs have nine inputs; any decoder of up to nine inputs is, therefore, compact and fast. But, there is also a need for much wider decoders, especially for address decoding in large microprocessor systems. The XC4000 family has four programmable decoders located on each edge of each device. Each of these wired-AND gates is capable of accepting up to 42 inputs on the XC4005 and 72 on the XC4013. These decoders may also be split in two when a large number of narrower decoders are required for a maximum of 32 per device. These dedicated decoders accept I/O signals and internal signals as inputs and generate a decoded internal signal in 18 ns, pin-to-pin. The XC4000A family has only two decoder AND gates per edge which, when split provide a maximum of 16 per device. Very large PALs can be emulated by ORing the decoder outputs in a CLB. This decoding feature covers what has long been considered a weakness of FPGAs. Users often resorted to external PALs for simple but fast decoding functions. Now, the dedicated decoders in the XC4000 can implement these functions efficiently and fast.

Higher Output Current: The 4-mA maximum output current specification of today's FPGAs often forces the user to add external buffers, cumbersome especially on bidirectional I/O lines. The XC4000 families solve many of these problems by increasing the maximum output sink current to 12 mA. Two adjacent outputs may be interconnected to increase the output sink current to 24 mA. The FPGA can thus drive short buses on a pc board. The XC4000A and XC4000H outputs can sink 24 mA per output and can double up for 48 mA.

While the XC2000 and XC3000 families used complementary output transistors, the XC4000 outputs are n-channel for both pull-down and pull-up, somewhat analogous to the classical totem pole used in TTL. The reduced output High level (VOH) makes circuit delays more symmetrical for TTL-threshold systems. The XC4000H outputs have an optional p-channel output transistor.

Abundant Routing Resources

Connections between blocks are made by metal lines with programmable switching points and switching matrices. Compared to the previous LCA families, these routing resources have been increased dramatically.The number of globally distributed signals has been increased from two to eight, and these lines have access to any clock or logic input. The designer of synchronous systems can now distribute not only several clocks, but also control signals, all over the chip, without having to worry about any skew.

There are more than twice as many horizontal and vertical Longlines that can carry signals across the length or width of the chip with minimal delay and negligible skew.The horizontal Longlines can be driven by 3-state buffers, and can thus be used as unidirectional or bidirectional data buses; or they can implement wide multiplexers or wired-AND functions.

Single-length lines connect the switching matrices that are located at every intersection of a row and a column of CLBs. These lines provide the greatest interconnect flexibility, but cause a delay whenever they go through a switching matrix. Double-length lines bypass every other matrix, and provide faster signal routing over intermediate distances.

Compared to the XC3000 family, the XC4000 families have more than double the routing resources, and they are arranged in a far more regular fashion. In older devices,

pass through a global buffer before arriving at the IOB. This eliminates the possibility of a data hold-time requirement at the external pin. The I1 and I2 signals that exit the block can each carry either the direct or registered input signal.

Output signals can be inverted or not inverted, and can pass directly to the pad or be stored in an edge-triggered flip-flop. Optionally, an output enable signal can be used to place the output buffer in a high-impedance state, implementing 3-state outputs or bidirectional I/O. Under configuration control, the output (OUT) and output enable (OE) signals can be inverted, and the slew rate of the output buffer can be reduced to minimize power bus transients when switching non-critical signals. Each XC4000-families output buffer is capable of sinking 12 mA; two adjacent output buffers can be wire-ANDed externally to sink up to 24 mA. In the XC4000A and XC4000H families, each output buffer can sink 24 mA.

There are a number of other programmable options in the IOB. Programmable pull-up and pull-down resistors are useful for tying unused pins to V_{CC} or ground to minimize power consumption. Separate clock signals are provided for the input and output registers; these clocks can be inverted, generating either falling-edge or rising-edge triggered flip-flops. As is the case with the CLB registers, a global set/reset signal can be used to set or clear the input and output registers whenever the RESET net is active.

Embedded logic attached to the IOBs contains test structures compatible with IEEE Standard 1149.1 for boundary-scan testing, permitting easy chip and board-level testing.

Programmable Interconnect

All internal connections are composed of metal segments with programmable switching points to implement the desired routing. An abundance of different routing resources is provided to achieve efficient automated routing. The number of routing channels is scaled to the size of the array; i.e., it increases with array size.

In previous generations of LCAs, the logic-block inputs were located on the top, left, and bottom of the block; outputs exited the block on the right, favoring left-to-right data flow through the device. For the third-generation family, the CLB inputs and outputs are distributed on all four sides of the block, providing additional routing flexibility (Figure 6). In general, the entire architecture is more symmetrical and regular than that of earlier generations, and is more suited to well-established placement and routing algorithms developed for conventional mask- programmed gate-array design.

There are three main types of interconnect, distinguished by the relative length of their segments: single-length lines, double-length lines, and Longlines. Note: The number of routing channels shown in Figures 6 and 9 are for illustration purposes only; the actual number of routing channels varies with array size. The routing scheme was designed for minimum resistance and capacitance of the average routing path, resulting in significant performance improvements.

The single-length lines are a grid of horizontal and vertical lines that intersect at a Switch Matrix between each block. Figure 6 illustrates the single-length interconnect lines

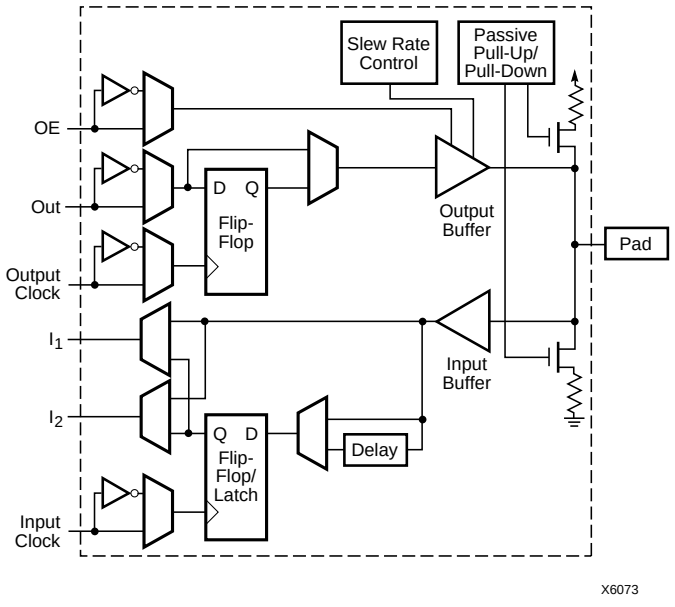


Figure 5. XC4000 and XC4000A Families Input/Output Block

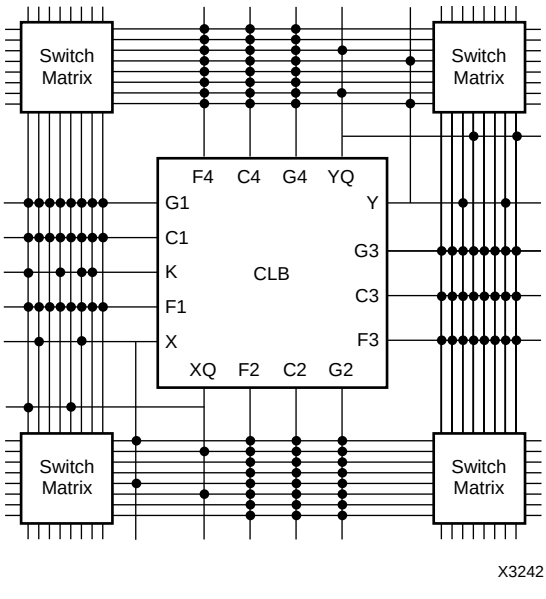


Figure 6. Typical CLB Connections to Adjacent Single-Length Lines

comparators, counters, data registers, decoders, encoders, I/O functions, latches, Boolean functions, RAM and ROM memory blocks, multiplexers, shift registers, and barrel shifters.

Designing with macros is as easy as designing with standard SSI/MSI functions. The 'soft macro' library contains detailed descriptions of common logic functions, but does not contain any partitioning or routing information. The performance of these macros depends, therefore, on how the PPR software processes the design. Relationally Placed Macros (RPMs), on the other hand, do contain predetermined partitioning and relative placement information, resulting in an optimized implementation for these functions. Users can create their own library elements – either soft macros or RPMs – based on the macros and primitives of the standard library.

X-BLOX is a graphics-based high-level description language (HDL) that allows designers to use a schematic editor to enter designs as a set of generic modules. The X-BLOX compiler optimizes the modules for the target device architecture, automatically choosing the appropriate architectural resources for each function.

The XACT design environment supports hierarchical design entry, with top-level drawings defining the major functional blocks, and lower-level descriptions defining the logic in each block. The implementation tools automatically combine the hierarchical elements of a design. Different hierarchical elements can be specified with different design entry tools, allowing the use of the most convenient entry method for each portion of the design.

Design Implementation

The design implementation tools satisfy the requirement for an automated design process. Logic partitioning, block placement and signal routing, encompassing the design implementation process, are performed by the Partition, Place, and Route program (PPR). The partitioner takes the logic from the entered design and maps the logic into the architectural resources of the FPGA (such as the logic blocks, I/O blocks, 3-state buffers, and edge decoders). The placer then determines the best locations for the blocks, depending on their connectivity and the required performance. The router finally connects the placed blocks together. The PPR algorithms result in the fully automatic implementation of most designs. However, for demanding applications, the user may exercise various degrees of control over the automated implementation process. Optionally, user-designated partitioning, placement, and routing information can be specified as part of the design entry process. The implementation of highly-structured designs can greatly benefit from the basic floorplanning techniques familiar to designers of large gate arrays.

The PPR program includes XACT-Performance, a feature that allows designers to specify the timing requirements along entire paths during design entry. Timing path analysis routines in PPR then recognize and accommodate the user-specified requirements. Timing requirements can be entered on the schematic in a form directly relating to the system requirements (such as the targeted minimum clock frequency, or the maximum allowable delay on the data path between two registers). So, while the timing of each individual net is not predictable (nor does it need to be), the overall performance of the system along entire signal paths is automatically tailored to match user-generated specifications.

The automated implementation tools are complemented by the XACT Design Editor (XDE), an interactive graphics-based editor that displays a model of the actual logic and routing resources of the FPGA. XDE can be used to directly view the results achieved by the automated tools. Modifications can be made using XDE; XDE also performs checks for logic connectivity and possible design-rule violations.

Design Verification

The high development cost associated with common mask-programmed gate arrays necessitates extensive simulation to verify a design. Due to the custom nature of masked gate arrays, mistakes or last-minute design changes cannot be tolerated. A gate-array designer must simulate and test all logic and timing using simulation software. Simulation describes what happens in a system under worst-case situations. However, simulation is tedious and slow, and simulation vectors must be generated. A few seconds of system time can take weeks to simulate.

Programmable-gate-array users, however, can use in-circuit debugging techniques in addition to simulation. Because Xilinx devices are reprogrammable, designs can be verified in the system in real time without the need for extensive simulation vectors.

The XACT development system supports both simulation and in-circuit debugging techniques. For simulation, the system extracts the post-layout timing information from the design database. This data can then be sent to the simulator to verify timing-critical portions of the design. Back-annotation – the process of mapping the timing information back into the signal names and symbols of the schematic – eases the debugging effort.

For in-circuit debugging, XACT includes a serial download and readback cable (XChecker) that connects the device in the system to the PC or workstation through an RS232 serial port. The engineer can download a design or a design revision into the system for testing. The designer can also single-step the logic, read the contents of the numerous flip-flops on the device and observe internal logic levels. Simple modifications can be downloaded into the system in a matter of minutes.

The XACT system also includes XDelay, a static timing analyzer. XDelay examines a design's logic and timing to calculate the performance along signal paths, identify possible race conditions, and detect set-up and hold-time violations. Timing analyzers do not require that the user generate input stimulus patterns or test vectors.

Summary

The result of eight years of FPGA design experience and feedback from thousands of customers, the XC4000 families combine architectural versatility, on-chip RAM, increased speed and gate complexity with abundant routing resources and new, sophisticated software to achieve fully automated implementation of complex, high-performance designs.

7400 Equivalents

	# of CLBs
'138	5
'139	2
'147	5
'148	6
'150	5
'151	3
'152	3
'153	2
'154	16
'157	2
'158	2
'160	5
'161	6
'162	8
'163	8
'164	4
'165s	9
'166	5
'168	7
'174	3
'194	5
'195	3
'280	3
'283	8
'298	2
'352	2
'390	3
'518	3
'521	3

Barrel Shifters

brlshft4	4
brlshft8	13

4-Bit Counters

cd4ce	3
cd4cle	5
cd4rle	6
cb4ce	3
cb4cle	6
cb4re	5

8- and 16-Bit Counters

cb8ce	6
cb8re	10
cc16ce	10
cc16cle	11
cc16cled	21

Identity Comparators

comp4	1
comp8	2
comp16	5

Magnitude Comparators

compm4	4
compm8	9
compm16	20

Decoders

d2-4e	2
d3-8e	4
d4-16e	16

Multiplexers

m2-1e	1
m4-1e	1
m8-1e	3
m16-1e	5

Registers

rd4r	2
rd8r	4
rd16r	8

Shift Registers

sr8ce	4
sr16re	8

RAMs

ram 16x4	2

Explanation of counter nomenclature

cb = binary counter
cd = BCD counter
cc = cascadable binary counter
d = bidirectional
l = loadable
x = cascadable
e = clock enable
r = synchronous reset
c = asynchronous clear

Figure 10. CLB Count of Selected XC4000 Soft Macros

Detailed Functional Description

XC4000 and XC4000A Input/Output Blocks

(For XC4000H family, see page 2-82)

The IOB forms the interface between the internal logic and the I/O pads of the LCA device. Under configuration control, the output buffer receives either the logic signal (.out) routed from the internal logic to the IOB, or the complement of this signal, or this same data after it has been clocked into the output flip-flop.

As a configuration option, each flip-flop (CLB or IOB) is initialized as either set or reset, and is also forced into this programmable initialization state whenever the global Set/Reset net is activated after configuration has been completed. The clock polarity of each IOB flip-flop can be configured individually, as can the polarity of the 3-state control for the output buffer.

Each output buffer can be configured to be either fast or slew-rate limited, which reduces noise generation and ground bounce. Each I/O pin can be configured with either an internal pull-up or pull down resistor, or with no internal resistor. Independent of this choice, each IOB has a pull-up resistor during the configuration process.

The 3-state output driver uses a totem pole n-channel output structure. V_{OH} is one n-channel threshold lower than V_{CC}, which makes rise and fall delays more symmetrical.

Family	Per IOB Source	Per IOB Sink	Per IOB Pair Sink	# Slew Modes
XC4000	4	12	24	2
XC4000A	4	24	48	4
XC4000H	4	24*	48	2

*XC4000H devices can sink only 4 mA configured for SoftEdge mode

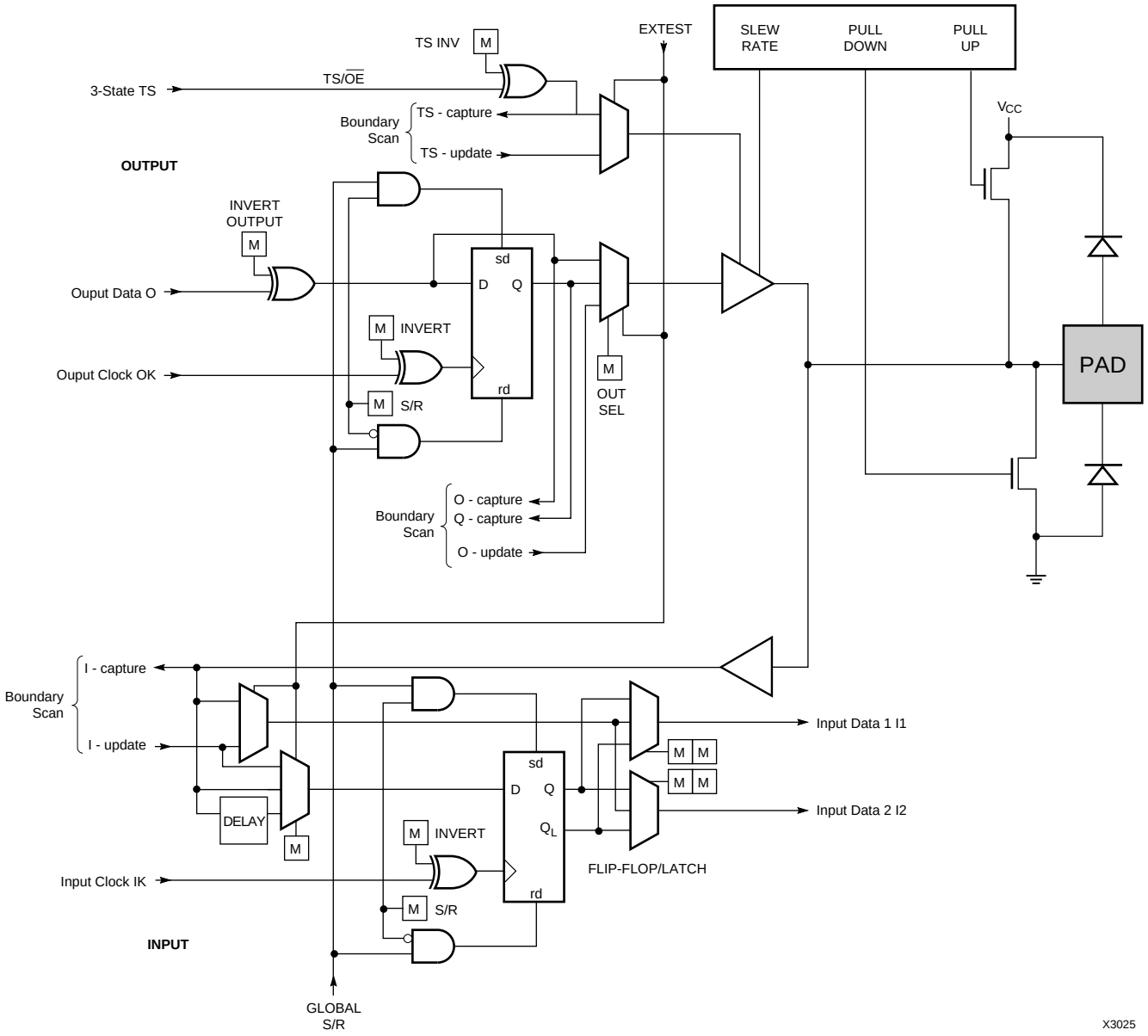


Figure 11. XC4000 and XC4000A I/O Block

The inputs drive TTL-compatible buffers with 1.2-V input threshold and a slight hysteresis of about 300 mV. These buffers drive the internal logic as well as the D-input of the input flip-flop.

Under configuration control, the set-up time of this flip-flop can be increased so that normal clock routing does not result in a hold-time problem. Note that the input flip-flop set-up time is defined between the data measured at the device I/O pin and the clock input at the IOB. Any clock routing delay must, therefore, be subtracted from this set-up time to arrive at the real set-up time requirement on the device pins. A short specified set-up time might, therefore, result in a negative set-up time at the device pins, i.e. a hold-time requirement, which is usually undesirable. The default long set-up time can tolerate more clock delay without causing a hold-time requirement. For faster input register setup time, with non-zero hold, attach a "NODELAY" property to the flip-flop. The exact method to accomplish this depends on the design entry tool.

The input block has two connections to the internal logic, I1 and I2. Each of these is driven either by the incoming data, by the master or by the slave of the input flip-flop.

Wide Decoders

The periphery of the chip has four wide decoder circuits at each edge (two in the XC4000A). The inputs to each decoder are any of the I1 signals on that edge plus one local interconnect per CLB row or column. Each decoder generates High output (resistor pull-up) when the AND condition of the selected inputs, or their complements, is true. This is analogous to the AND term in typical PAL devices. Each decoder can be split at its center.

The decoder outputs can drive CLB inputs so they can be combined with other logic, or to form a PAL-like AND/OR structure. The decoder outputs can also be routed directly to the chip outputs. For fastest speed, the output should be on the same chip edge as the decoder.

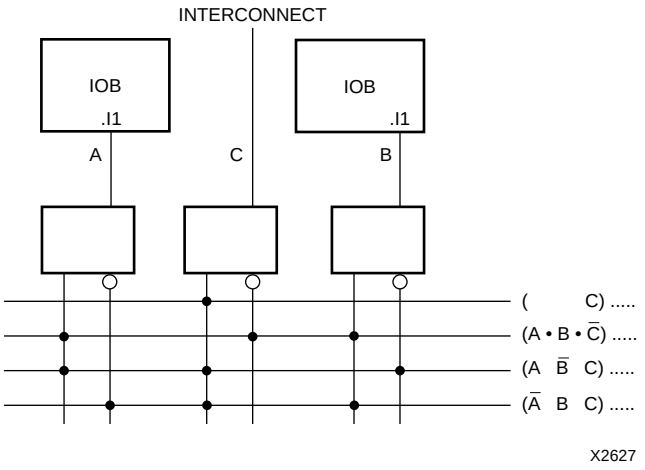


Figure 12. **Example of Edge Decoding.** Each row or column of CLBs provide up to three variables (or their complements)

Configurable Logic Blocks

Configurable Logic Blocks implement most of the logic in an LCA device. Two 4-input function generators (F and G) offer unrestricted versatility. A third function generator (H) can combine the outputs of F and G with a ninth input variable, thus implementing certain functions of up to nine variables, like parity check or expandable-identity comparison of two sets of four inputs.

The four control inputs C1 through C4 can each generate any one of four logic signals, used in the CLB.

- Enable Clock, Asynchronous Preset/Reset, DIN, and H1, when the memory function is disabled, or
- Enable Clock, Write Enable, D0, and D1, when the memory function is enabled.

Since the function-generator outputs are brought out independently of the flip-flop outputs, and DIN and H1 can be used as direct inputs to the two flip-flops, the two combinatorial and the two sequential functions in the CLB can be used independently. This versatility increases logic density and simplifies routing.

The asynchronous flip-flop input can be configured as either set or reset. This configuration option also determines the state in which the flip-flops become operational after configuration, as well as the effect of an externally or internally applied Set/Reset during normal operation.

Fast Carry Logic

The CLBs can generate the arithmetic-carry output for incoming operands, and can pass this extra output on to the next CLB function generator above or below. This connection is independent of normal routing resources and it is, presently, only supported by Hard Macros. A later software release will accommodate Soft Macros and will permit graphic editing of the fast logic circuitry. This fast carry logic is one of the most significant improvements in the XC4000 families, speeding up arithmetic and counting into the 60-MHz range.

Using Function Generators as RAMs

Using XC4000 devices, the designer can write into the latches that hold the configuration content of the function generators. Each function generator can thus be used as a small Read/Write memory, or RAM. The function generators in any CLB can be configured in three ways.

- Two 16 x 1 RAMs with two data inputs and two data outputs – identical or, if preferred, different addressing for each RAM
- One 32 x 1 RAM with one data input and one data output
- One 16 x 1 RAM plus one 5-input function generator

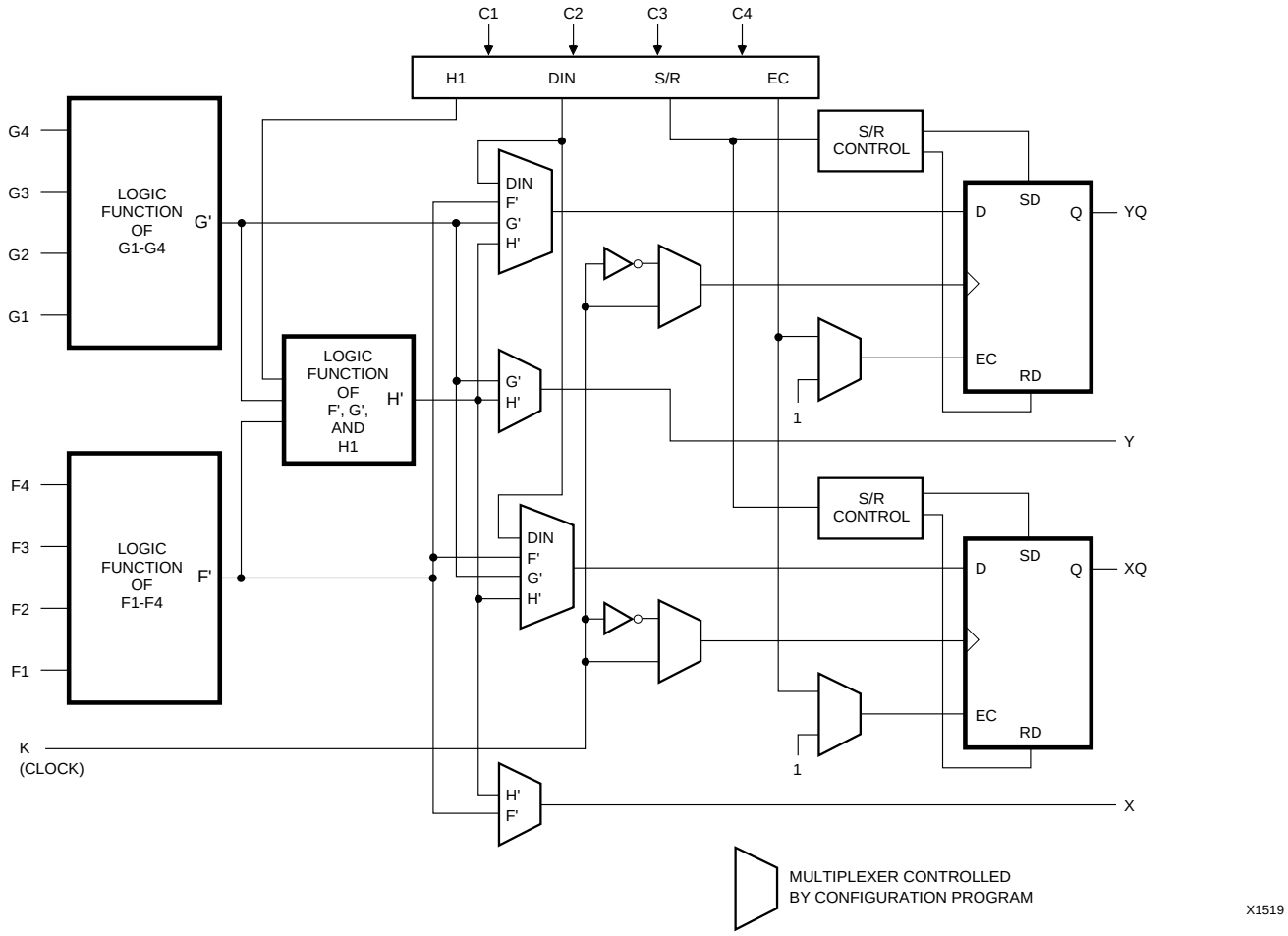


Figure 13. Simplified Block Diagram of XC4000 Configurable Logic Block

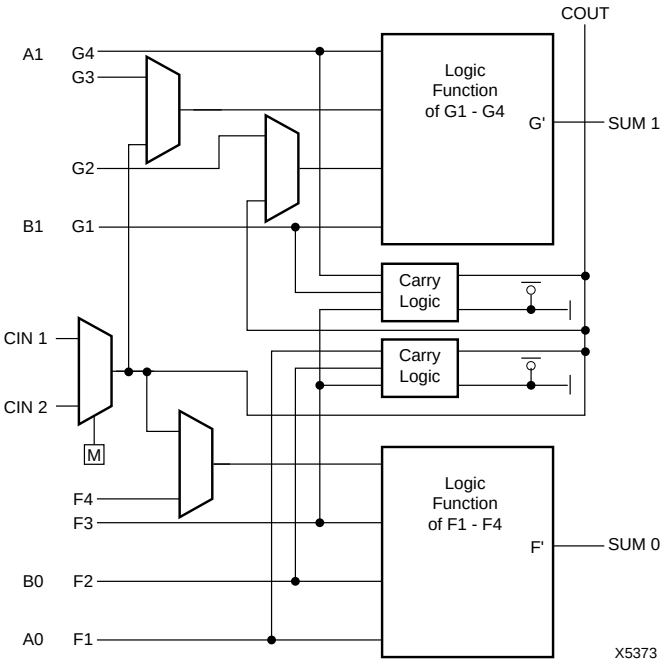


Figure 14. Fast Carry Logic in Each CLB

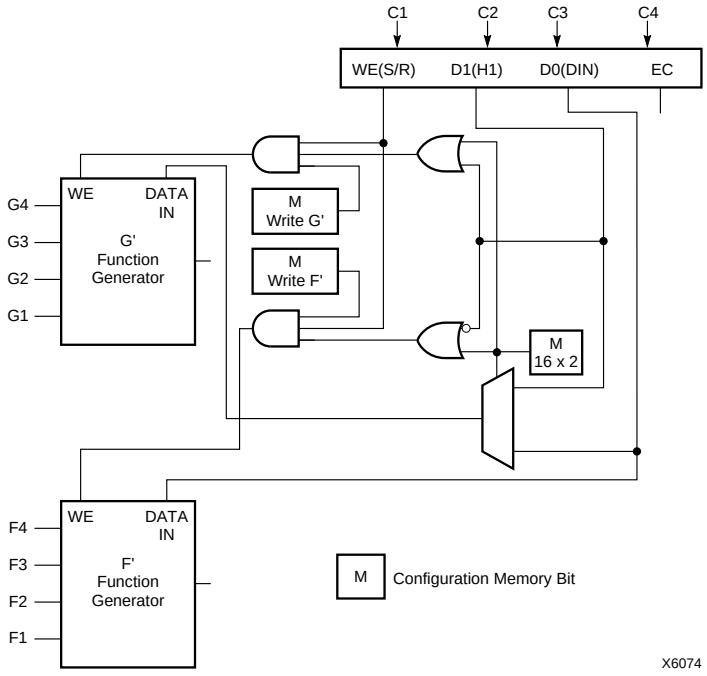


Figure 15. CLB Function Generators Can Be Used as Read/Write Memory Cells

Boundary Scan

Boundary Scan is becoming an attractive feature that helps sophisticated systems manufacturers test their PC boards more safely and more efficiently. The XC4000 family implements IEEE 1149.1-compatible BYPASS, PRELOAD/SAMPLE and EXTEST Boundary-Scan instructions. When the Boundary-Scan configuration option is selected, three normal user I/O pins become dedicated inputs for these functions.

The "bed of nails" has been the traditional method of testing electronic assemblies. This approach has become less appropriate, due to closer pin spacing and more sophisticated assembly methods like surface-mount technology and multi-layer boards. The IEEE Boundary Scan standard 1149.1 was developed to facilitate board-level testing of electronic assemblies. Design and test engineers can imbed a standard test logic structure in their electronic design. This structure is easily implemented with the serial and/or parallel connections of a four-pin interface on any Boundary-Scan-compatible IC. By exercising these signals, the user can serially load commands and data into these devices to control the driving of their outputs and to examine their inputs. This is an improvement over bed-of-nails testing. It avoids the need to overdrive device outputs, and it reduces the user interface to four pins. An optional fifth pin, a reset for the control logic, is described in the standard but is not implemented in the Xilinx part.

The dedicated on-chip logic implementing the IEEE 1149.1 functions includes a 16-state machine, an instruction register and a number of data registers. A register operation begins with a *capture* where a set of data is parallel loaded into the designated register for shifting out. The next state is *shift*, where captured data are shifted out while the desired data are shifted in. A number of states are provided for Wait operations. The last state of a register sequence is the *update* where the shifted content of the register is loaded into the appropriate instruction- or data-holding register, either for instruction-register decode or for data-register pin control.

The primary data register is the Boundary-Scan register. For each IOB pin in the LCA device, it includes three bits of shift register and three *update* latches for: in, out and 3-state control. Non-IOB pins have appropriate partial bit population for in or out only. Each Extest Capture captures all available input pins.

The other standard data register is the single flip-flop *bypass* register. It resynchronizes data being passed through a device that need not be involved in the current scan operation. The LCA device provides two user nets (BSCAN.SEL1 and BSCAN.SEL2) which are the decodes of two user instructions. For these instructions, two corresponding nets (BSCAN.TDO1 and BSCAN.TDO2) allow user scan data to be shifted out on TDO. The data register clock (BSCAN.DRCK) is available for control of test logic which the user may wish to implement with CLBs. The NAND of TCK and Run-test-idle is also provided (BSCAN.IDLE).

The XC4000 Boundary Scan instruction set also includes instructions to configure the device and read back the configuration data.

Table 4. Boundary Scan Instruction

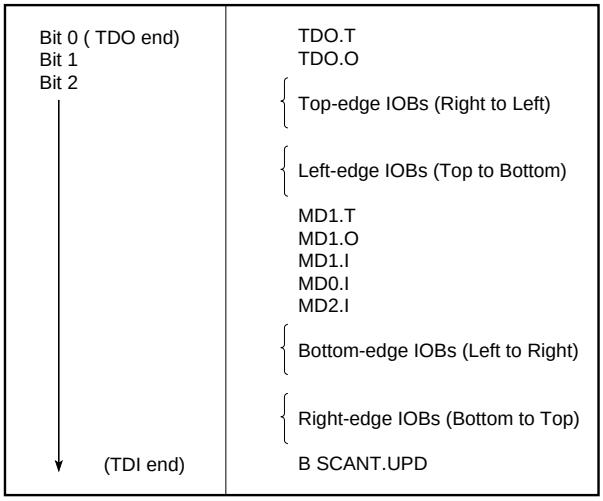
Instruction I_2	I_1	I_0	Test Selected	TDO Source	I/O Data Source
0	0	0	Extest	DR	DR
0	0	1	Sample/Preload	DR	Pin/Logic
0	1	0	User 1	TDO1	Pin/Logic
0	1	1	User 2	TDO2	Pin/Logic
1	0	0	Readback	Readback Data	Pin/Logic
1	0	1	Configure	DOUT	Disabled
1	1	0	Reserved	—	—
1	1	1	Bypass	Bypass Reg	Pin/Logic

X2679

Bit Sequence

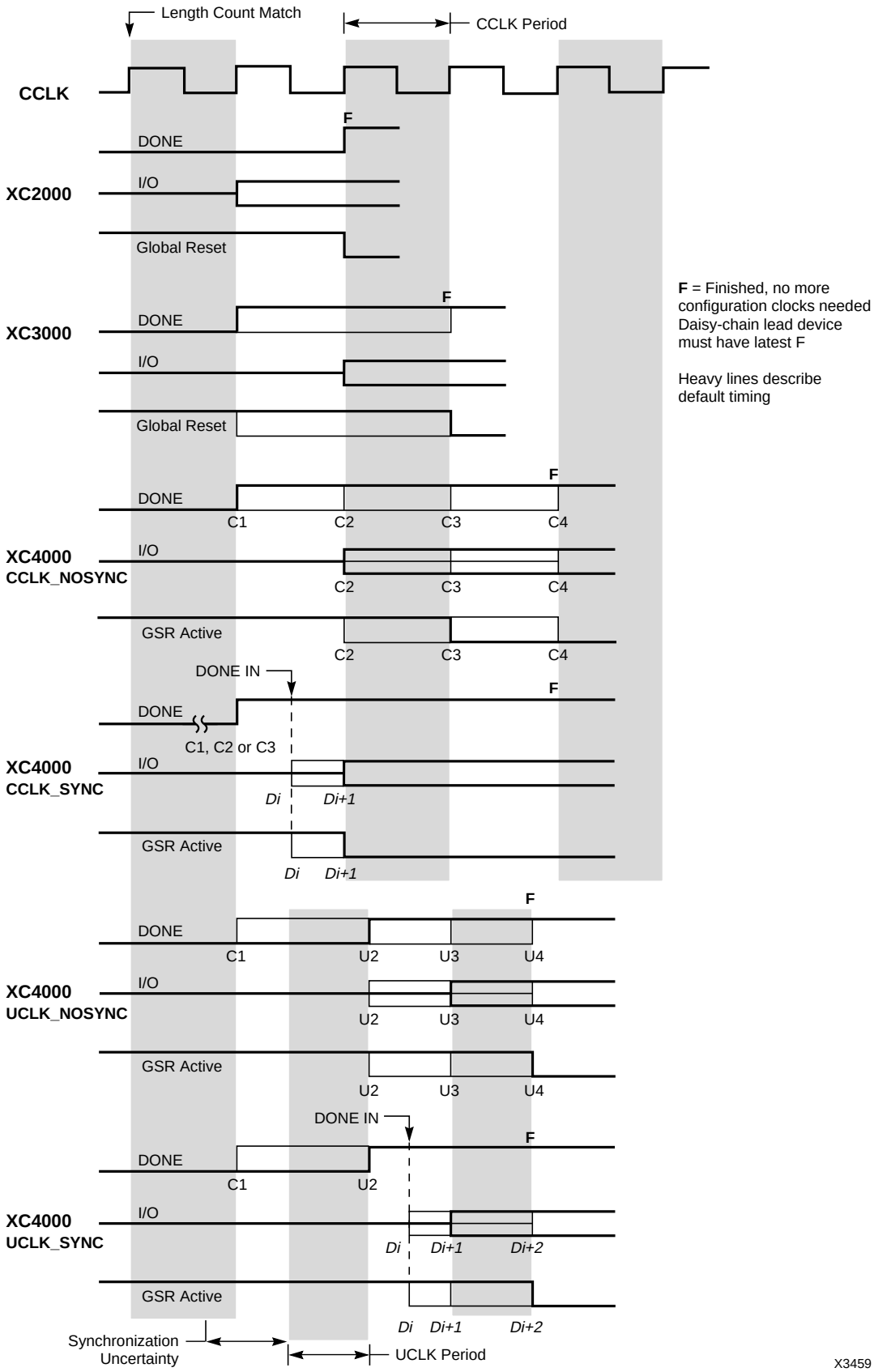
The bit sequence within each IOB is: in, out, 3-state. From a cavity-up (XDE) view of the chip, starting in the upper right chip corner, the Boundary-Scan data-register bits have the following order.

Table 5. Boundary Scan Order



X6075

The data register also includes the following non-pin bits: TDO.T, and TDO.I, which are always bits 0 and 1 of the data register, respectively, and BSCANT.UPD which is always the last bit of the data register. These three Boundary-Scan bits are special-purpose Xilinx test signals. PROGRAM, CCLK and DONE are not included in the Boundary-Scan register. For more information regarding Boundary Scan, refer to XAPP 017.001, *Boundary Scan in XC4000 Devices*.



Note: Thick lines are default option.

Figure 21. Start-up Timing

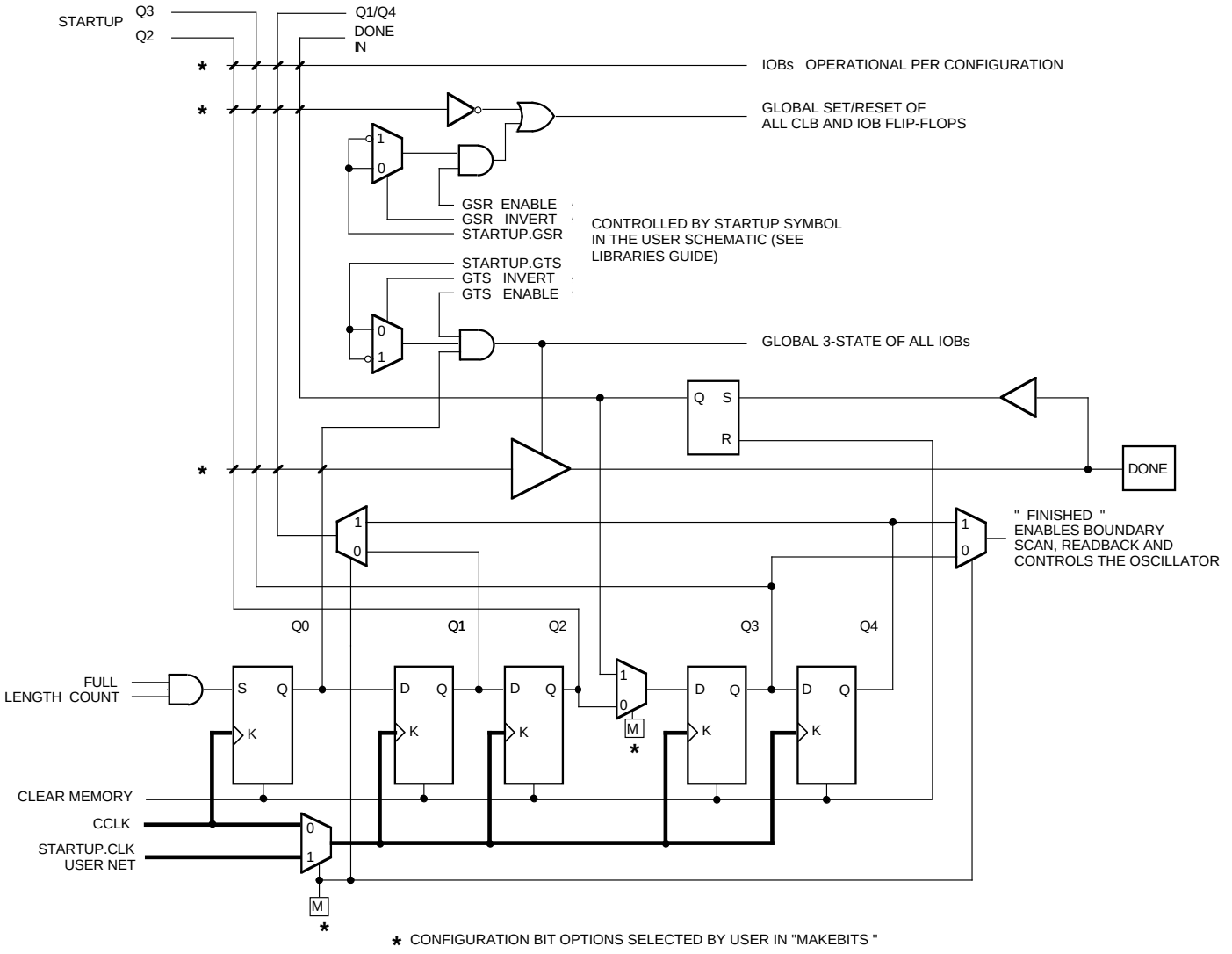


Figure 22. Start-up Logic

All Xilinx FPGAs of the XC2000, XC3000, XC4000 familiies use a compatible bitstream format and can, therefore, be connected in a daisy-chain in an arbitrary sequence. There is however one limitation. The lead device must belong to the highest family in the chain. If the chain contains XC4000 devices, the master cannot be an XC2000 or XC3000 device; if the daisy-chain contains XC3000 devices, the master cannot be an XC2000 device. The reason for this rule is shown in Figure 21 on the previous page. Since all devices in the chain store the same length count value and generate or receive one common sequence of CCLK pulses, they all recognize length-count match on the same CCLK edge, as indicated on the left edge of Figure 21. The master device will then drive additional CCLK pulses until it reaches its finish point F. The different families generate or require different numbers of additional CCLK pulses until they reach F.

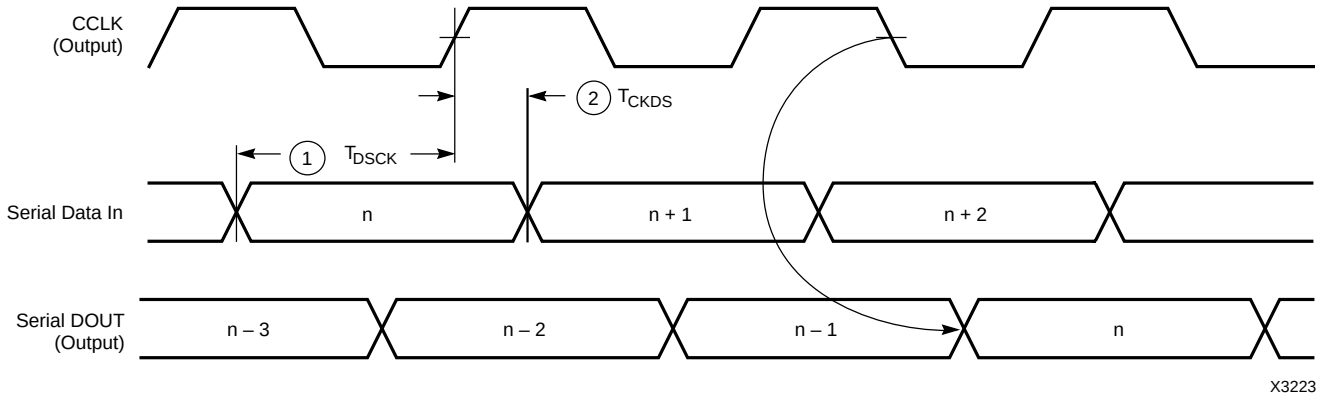
Not reaching F means that the device does not really finish its configuration, although DONE may have gone High, the outputs became active, and the internal RESET was released. The user has some control over the relative timing of these events and can, therefore, make sure that they occur early enough.

But, for XC4000, not reaching F means that READBACK cannot be initiated and most Boundary Scan instructions cannot be used.This limitation has been critized by designers who want to use an inexpensive lead device in peripheral mode and have the more precious I/O pins of the XC4000 devices all available for user I/O. Here is a solution for that case.

One CLB and one IOB in the lead XC3000 device are used to generate the additional CCLK pulse required by the XC4000 devices. When the lead device removes the internal RESET signal, the 2-bit shift register responds to its clock input and generates an active Low output signal for the duration of the subsequent clock period. An external connection between this output and CCLK thus creates

externally, the device determines its configuration mode by capturing its status inputs, and is ready to start the configuration process. A master device waits an additional up to 250 µs to make sure that all slaves in the potential daisy-chain have seen INIT being High.

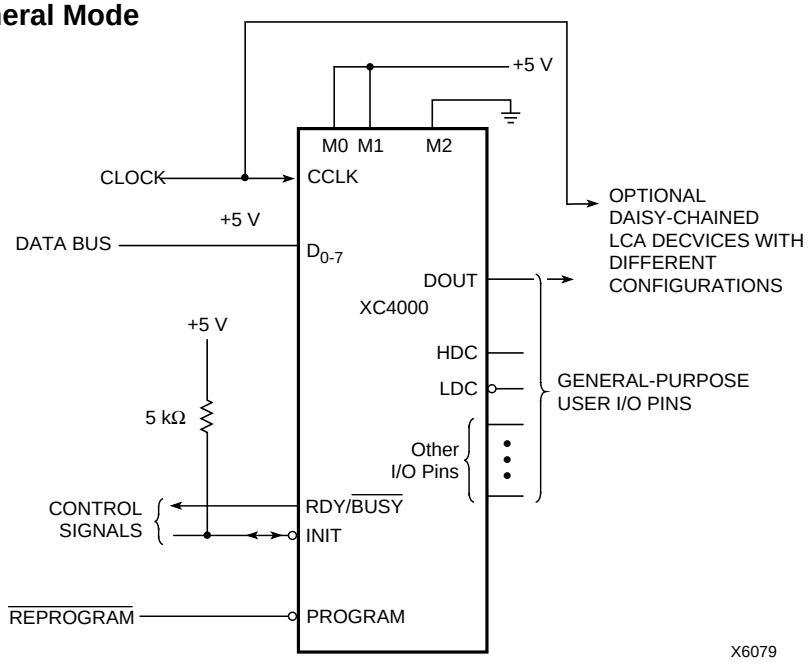
Master Serial Mode Programming Switching Characteristics



	Description	Symbol		Min	Max	Units
CCLK	Data In setup	1	T_{DSCK}	20		ns
	Data In hold	2	T_{CKDS}	0		ns

Notes: 1. At power-up, V_{CC} must rise from 2.0 V to Vcc min in less than 25 ms, otherwise delay configuration by pulling PROGRAM Low until V_{CC} is valid.
2. Configuration can be controlled by holding INIT Low with or until after the INIT of all daisy-chain slave mode devices is High.
3. Master-serial-mode timing is based on testing in slave mode.

Synchronous Peripheral Mode



Synchronous Peripheral mode can also be considered Slave Parallel mode. An external signal drives the CCLK input(s) of the LCA device(s). The first byte of parallel configuration data must be available at the D inputs of the lead LCA device a short set-up time before the rising CCLK edge. Subsequent data bytes are clocked in on every eighth consecutive rising CCLK edge. The same CCLK edge that accepts data, also causes the RDY/BUSY output to go High for one CCLK period. The pin name is a misnomer. In Synchronous Peripheral mode it is really an ACKNOWLEDGE signal. Synchronous operation does not require this response, but it is a meaningful signal for test purposes.

The lead LCA device serializes the data and presents the preamble data (and all data that overflows the lead device) on its DOUT pin. There is an internal delay of 1.5 CCLK periods, which means that DOUT changes on the falling CCLK edge, and the next LCA device in the daisy-chain accepts data on the subsequent rising CCLK edge. In order to complete the serial shift operation, 10 additional CCLK rising edges are required after the last data byte has been loaded, plus one more CCLK cycle for each daisy-chained device.

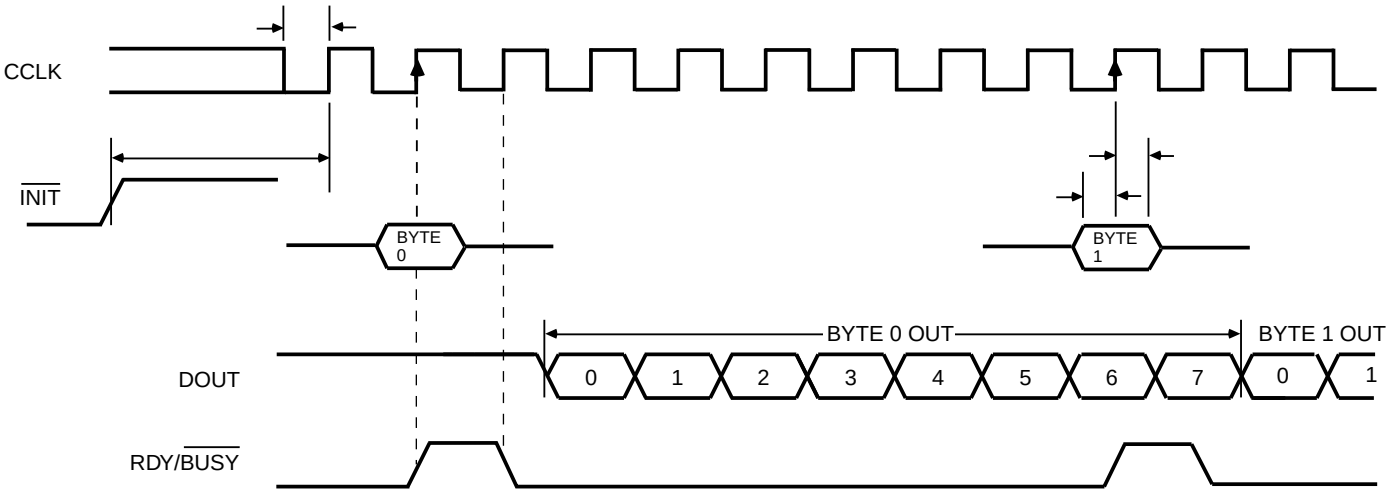
How to Delay Configuration After Power-Up

There are two methods to delay configuration after power-up: Put a logic Low on the PROGRAM input, or pull the bidirectional INIT pin Low, using an open-collector (open-drain) driver. (See also Figure 20 on page 2-27).

A Low on the PROGRAM input is the more radical approach, and is recommended when the power-supply rise time is excessive or poorly defined. As long as PROGRAM is Low, the XC4000 device keeps clearing its configuration memory. When PROGRAM goes High, the configuration memory is cleared one more time, followed by the beginning of configuration, provided the INIT input is not externally held Low. Note that a Low on the PROGRAM input automatically forces a Low on the INIT output.

Using an open-collector or open-drain driver to hold INIT Low before the beginning of configuration, causes the LCA device to wait after having completed the configuration memory clear operation. When INIT is no longer held Low externally, the device determines its configuration mode by capturing its status inputs, and is ready to start the configuration process. A master device waits an additional max 250 µs to make sure that all slaves in the potential daisy-chain have seen INIT being High.

Synchronous Peripheral Mode Programming Switching Characteristics



X6096

	Description	Symbol		Min	Max	Units
CCLK	INIT (High) Setup time required	1	T_{IC}	5		µs
	D0-D7 Setup time required	2	T_{DC}	60		ns
	D0-D7 Hold time required	3	T_{CD}	0		ns
	CCLK High time		T_{CCH}	50		ns
	CCLK Low time		T_{CCL}	60		ns
	CCLK Frequency		F_{CC}		8	MHz

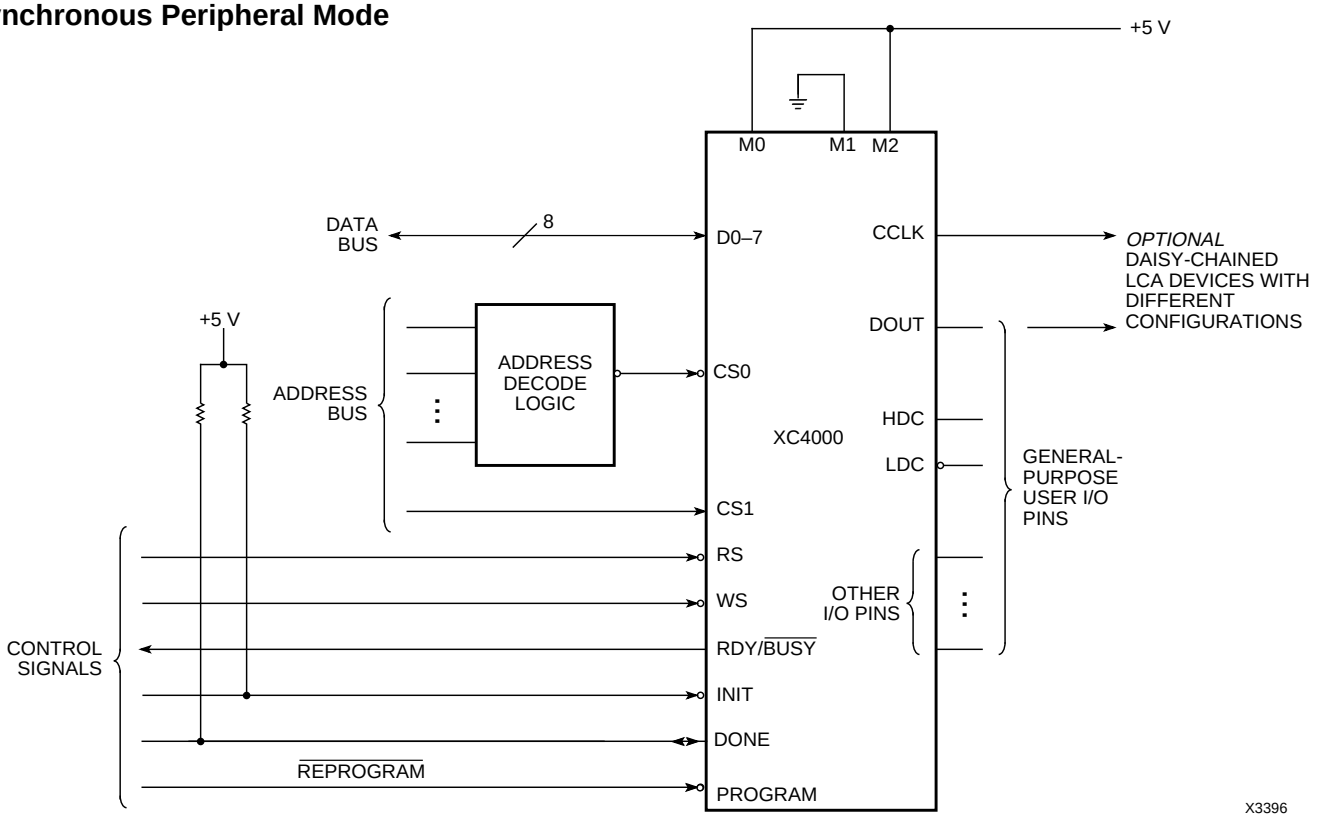
Notes: Peripheral Synchronous mode can be considered Slave Parallel mode. An external CCLK provides timing, clocking in the **first** data byte on the **second** rising edge of CCLK after INIT goes High. Subsequent data bytes are clocked in on every eighth consecutive rising edge of CCLK.

The RDY/BUSY line goes High for one CCLK period after data has been clocked in, although synchronous operation does not require such a response.

The pin name RDY/BUSY is a misnomer; in Synchronous Peripheral mode this is really an ACKNOWLEDGE signal.

Note that data starts to shift out serially on the DOUT pin 0.5 CLK periods after it was loaded in parallel. This obviously requires additional CCLK pulses after the last byte has been loaded.

Asynchronous Peripheral Mode



Write to LCA

Asynchronous Peripheral mode uses the trailing edge of the logic AND condition of the CS0, CS1 and WS inputs to accept byte-wide data from a microprocessor bus. In the lead LCA device, this data is loaded into a double-buffered UART-like parallel-to-serial converter and is serially shifted into the internal logic. The lead LCA device presents the preamble data (and all data that overflows the lead device) on the DOUT pin.

The RDY/BUSY output from the lead LCA device acts as a handshake signal to the microprocessor. RDY/BUSY goes Low when a byte has been received, and goes High again when the byte-wide input buffer has transferred its information into the shift register, and the buffer is ready to receive new data. The length of the BUSY signal depends on the activity in the UART. If the shift register had been empty when the new byte was received, the BUSY signal lasts for only two CCLK periods. If the shift register was still full when the new byte was received, the BUSY signal can be as long as nine CCLK periods.

Note that after the last byte has been entered, only seven of its bits are shifted out. CCLK remains High with DOUT equal to bit 6 (the next-to-last bit) of the last byte entered. The READY/BUSY handshake can be ignored if the delay from any one Write to the end of the next Write is guaranteed to be longer than 10 CCLK periods,i.e. longer than 20 µs.

Status Read

The logic AND condition of the CS0, CS1and RS inputs puts the device status on the Data bus.

D7 = High indicates Ready
D7 - Low indicates Busy
D0 through D6 go unconditionally High

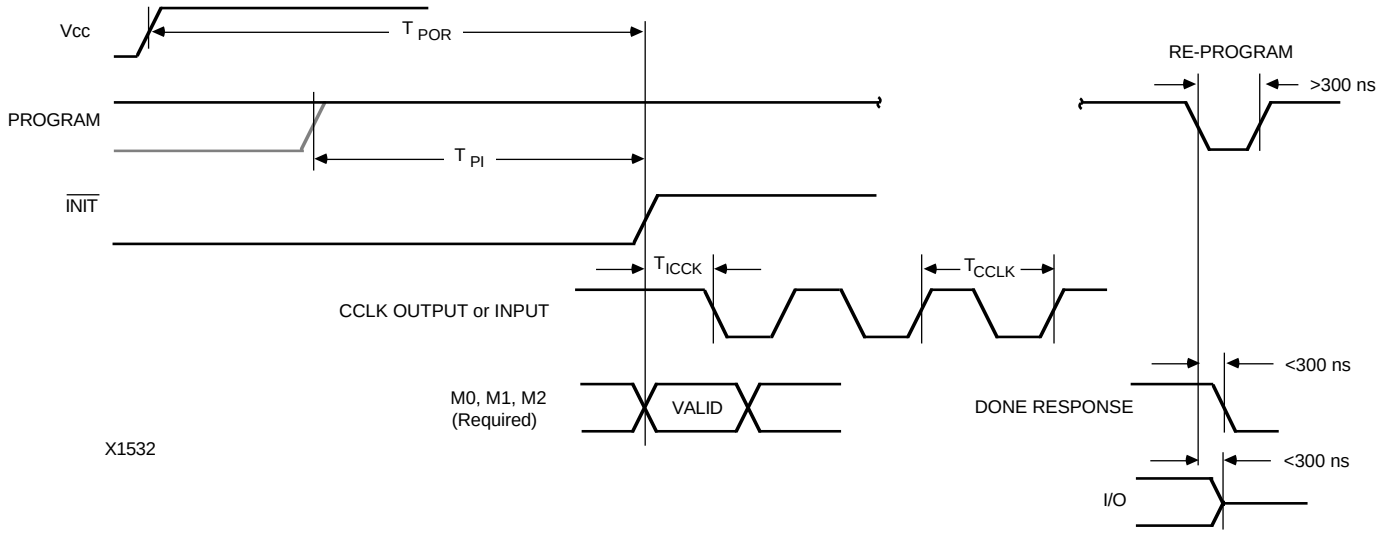
It is mandatory that the whole start-up sequence be started and completed by one byte-wide input. Otherwise, the pins used as Write Strobe or Chip Enable might become active outputs and inteffere with the final byte transfer. If this transfer does not occur, the start-up sequence will not be completed all the way to the finish (point F in Figure 21 on page 2-29). At worst, the internal reset will not be released; at best, Readback and Boundary Scan will be inhibited. The length-count value, as generated by MAKEPROM, is supposed to ensure that these problems never occur.

Although RDY/BUSY is brought out as a separate signal, microprocessors can more easily read this information on one of the data lines. For this purpose, D7 represents the RDY/BUSY status when RS is Low, WS is High, and the two chip select lines are both active.

How to Delay Configuration After Power-Up

There are two methods to delay configuration after power-up: Put a logic Low on the PROGRAM input, or pull the bidirectional INIT pin Low, using an open-collector (open-drain) driver. (See also Figure 20 on page 2-27).

General LCA Switching Characteristics



Master Modes

	Symbol	Min	Max	Units
Power-On-Reset M0 = High M0 = Low	T_{POR} T_{POR}	10 40	40 130	ms ms
Program Latency	T_{PI}	30	200	µs per CLB column
CCLK (output) Delay period (slow) period (fast)	T_{ICCK} T_{CCLK} T_{CCLK}	40 640 100	250 2000 250	µs ns ns

Slave and Peripheral Modes

	Symbol	Min	Max	Units
Power-On-Reset	T_{POR}	10	33	ms
Program Latency	T_{PI}	30	200	µs per CLB column
CCLK (input) Delay (required) period (required)	T_{ICCK} T_{CCLK}	4 100		µs ns

Note: At power-up, V_{CC} must rise from 2.0 V to V_{CC} min in less than 25 ms, otherwise delay configuration using PROGRAM until V_{CC} is valid.

Pin Descriptions

Permanently Dedicated Pins

V_{CC}

Eight or more (depending on package type) connections to the nominal +5 V supply voltage. All must be connected.

GND

Eight or more (depending on package type) connections to ground. All must be connected.

CCLK

During configuration, Configuration Clock is an output of the LCA in Master modes or asynchronous Peripheral mode, but is an input to the LCA in Slave mode and Synchronous Peripheral mode.

After configuration, CCLK has a weak pull-up resistor and can be selected as Readback Clock.

DONE

This is a bidirectional signal, configurable with or without a pull-up resistor of 2 to 8 kΩ.

As an output, it indicates the completion of the configuration process. The configuration program determines the exact timing, the clock source for the Low-to-High transition, and enable of the pull-up resistor.

As an input, a Low level on DONE can be configured to delay the global logic initialization or the enabling of outputs

---

PROGRAM

This is an active Low input that forces the LCA to clear its configuration memory.

When PROGRAM goes High, the LCA finishes the current clear cycle and executes another complete clear cycle, before it goes into a WAIT state and releases INIT.

User I/O Pins that can have Special Functions

RDY/BUSY

During peripheral modes, this pin indicates when it is appropriate to write another byte of data into the LCA device. The same status is also available on D7 in asynchronous peripheral mode, if a read operation is performed when the device is selected. After configuration, this is a user-programmable I/O pin.

RCLK

During Master Parallel configuration, each change on the A0-15 outputs is preceded by a rising edge on RCLK, a redundant output signal. After configuration, this is a user-programmable I/O pin.

M0, M1, M2

As Mode inputs, these pins are sampled before the start of configuration to determine the configuration mode to be used.

After configuration, M0 and M2 can be used as inputs, and M1 can be used as a 3-state output. These three pins have no associated input or output registers.

These pins can be user inputs or outputs only when called out by special schematic definitions.

TDO

If boundary scan is used, this is the Test Data Output.

If boundary scan is not used, this pin is a 3-state output without a register, after configuration is completed.

This pin can be user output only when called out by special schematic definitions.

TDI,TCK, TMS

If boundary scan is used, these pins are Test Data In, Test Clock, and Test Mode Select inputs respectively coming directly from the pads, bypassing theIOBs. These pins can also be used as inputs to the CLB logic after configuration is completed.

If the boundary scan option is not selected, all boundary scan functions are inhibited once configuration is completed, and these pins become user-programmable I/O.

Note:
The XC4000 families have no Powerdown control input; use the global 3-state net instead.
The XC4000 families have no dedicated Reset input. Any user I/O can be configured to drive the global Set/Reset net.

HDC

High During Configuration is driven High until configuration is completed. It is available as a control output indicating that configuration is not yet completed. After configuration, this is a user-programmable I/O pin.

LDC

Low During Configuration is driven Low until configuration. It is available as a control output indicating that configuration is not yet completed. After configuration, this is a user-programmable I/O pin.

INIT

Before and during configuration, this is a bidirectional signal. An external pull-up resistor is recommended.

As an active-Low open-drain output, INIT is held Low during the power stabilization and internal clearing of the configuration memory. As an active-Low input, it can be used to hold the LCA device in the internal WAIT state before the start of configuration. Master mode devices stay in a WAIT state an additional 30 to 300 µs after INIT has gone High.

During configuration, a Low on this output indicates that a configuration data error has occurred. After configuration, this is a user-programmable I/O pin.

PGCK1 - PGCK4

Four Primary Global Inputs each drive a dedicated internal global net with short delay and minimal skew. If not used for this purpose, any of these pins is a user-programmable I/O.

SGCK1 - SGCK4

Four Secondary Global Inputs can each drive a dedicated internal global net, that alternatively can also be driven from internal logic. If not used for this purpose, any of these pins is a user-programmable I/O pin.

CS0, CS1, WS, RS

These four inputs are used in Peripheral mode. The chip is selected when CS0 is Low and CS1 is High. While the chip is selected, a Low on Write Strobe (WS) loads the data present on the D0 - D7 inputs into the internal data buffer; a Low on Read Strobe (RS) changes D7 into a status output: High if Ready, Low if Busy, and D0…D6 are active Low. WS and RS should be mutually exclusive, but if both are Low simultaneously, the Write Strobe overrides. After configuration, these are user-programmable I/O pins.

A0 - A17

During Master Parallel mode, these 18 output pins address the configuration EPROM. After configuration, these are user-programmable I/O pins.

D0 - D7

During Master Parallel and Peripheral configuration modes, these eight input pins receive configuration data. After configuration, they are user-programmable I/O pins.

DIN

During Slave Serial or Master Serial configuration modes, this is the serial configuration data input receiving data on the rising edge of CCLK.

During parallel configuration modes, this is the D0 input. After configuration, DIN is a user-programmable I/O pin.

DOUT

During configuration in any mode, this is the serial configuration data output that can drive the DIN of daisy-chained slave LCA devices. DOUT data changes on the falling edge of CCLK, one-and-a-half CCLK periods after it was received at the DIN input. After configuration, DOUT is a user-programmable I/O pin.

Unrestricted User-Programmable I/O Pins

I/O

A pin that can be configured to be input and/or output after configuration is completed. Before configuration is completed, these pins have an internal high-value pull-up resistor that defines the logic level as High.

Before and during configuration, all outputs that are not used for the configuration process are 3-stated with a 50 kΩ to 100 kΩ pull-up resistor.

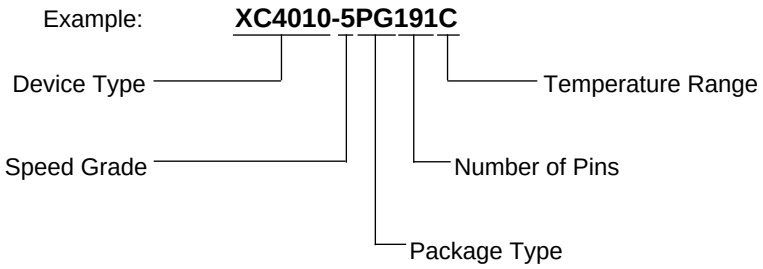
For a detailed description of the device architecture, see page 2-9 through 2-31.

For a detailed description of the configuration modes and their timing, see pages 2-32 through 2-55.

For detailed lists of package pinouts, see pages 2-57 through 2-67, 2-70, 2-81 through 2-85, and 2-100 through 2-101.

For package physical dimensions and thermal data, see Section 4.

Ordering Information



Component Availability

PINS		84	100			120	144	156	160	164	191	196	208		223	225	240		299	304
TYPE		PLAST. PLCC	PLAST. PQFP	PLAST. VQFP	TOP BRAZED CQFP	CERAM. PGA	PLAST. TQFP	CERAM PGA	PLAST. PQFP	TOP BRAZED CQFP	CERAM. PGA	TOP BRAZED CQFP	PLAST. PQFP	METAL PQFP	CERAM. PGA	PLAST. BGA	PLAST. PQFP	METAL PQFP	METAL PQFP	HI QUAD
CODE		PC84	PQ100	VQ100	CB100	PG120	TQ144	PG156	PQ160	CB164	PG191	CB196	PQ208	MQ208	PG223	BG225	PQ240	MQ240	PG299	HQ304
XC4003	-6	C I	C I			C I														
	-5	C	C			C														
	-4	C	C			C														
XC4005	-10							M B		M B										
	-6	C I	C I					C I M B	C I	M B			C I							
	-5	C I	C I					C I	C I				C I							
	-4	C	C					C	C				C							
XC4006	-6	C I						C I	C I				C I							
	-5	C I						C I	C I				C I							
	-4	C						C	C				C							
XC4008	-6	C I							C I		C I		C I	C I						
	-5	C I							C I		C I		C I	C I						
	-4	C							C		C		C	C						
XC4010	-10										M B	M B								
	-6	C I							C I		C I M B	M B	C I	C I		C I				
	-5	C I							C I		C I		C I	C I		C I				
	-4	C							C		C		C	C		C				
XC4010D	-6	C I							C I				C I			C I				
	-5	C I							C I				C I			C I				
	-4								C				C			C				
XC4013	-6								C I				C I	C I	CI (M B)	C I	CI	C I		
	-5								C I				C I	C I	C I	C I	C I	C I		
	-4								C				C	C	C	C	CI	C		
XC4013D	-6								C I				C I			C I	C I			
	-5								C I				C I			C I	C I			
	-4								C				C			C	C			
XC4020	-6												(C I)		(C I)		(C I)		(C I)	
	-5												(C I)		(C I)		(C I)		(C I)	
	-4												(C)		(C)		(C)		(C)	
XC4025	-6														C			C I	C I	C I
	-5														C			C I	C I	C I
	-4																			
XC4002A	-6	C I	C I	C I		C I														
	-5	C	C	C		C														
	-4																			
XC4003A	-10				M B	M B														
	-6	C I	C I	C I	M B	C I M B														
	-5	C	C	C		C														
	-4	C	C	C		C														
XC4004A	-6	C I				C I	C I		C I											
	-5	C				C	C		C											
	-4																			
XC4005A	-6	C I					C I	C I	C I				C I							
	-5	C I					C I	C I	C I				C I							
	-4	C					C	C	C				C							
XC4003H	-6										C I		C I							
	-5										C		C							
XC4005H	-6														C I		C I	C I		
	-5														C		C	C		

C = Commercial = 0° to +85° C I = Industrial = -40° to +100° C M = Mil Temp = -55° to +125° C
B = MIL-STD-883C Class B Parentheses indicate future product plans